

a device arranged to select at least one detection section from the plurality of detection sections and to calculate a position of an object surface based upon an output of the selected detection section.

38. A lithography system, comprising:

an electrostatic sensor having a plurality of detection sections; and

a controller that selects at least one detection section from the plurality of detection sections and detects a height of a substrate surface based upon an output of the selected detection section.

39. The system according to claim 38, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section based on a dimension of the shot region.

40. The system according to claim 38, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section based on a position, of the shot region, in the wafer.

41. The system according to claim 38, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section based on an arrangement of chip regions in the shot region.

42. A device manufacturing method comprising the steps of:

exposing the substrate using the lithography system of claim 38; and

developing the exposed substrate.

43. A lithography system, comprising:

a plurality of electrostatic sensors each having a plurality of detection sections;

and

a controller that selects at least one detection section from each of the plurality of electrostatic sensors and detects a height of a substrate surface based upon outputs of the selected detection sections of the plurality of electrostatic sensors.

44. The system according to claim 43, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section from each of the plurality of electrostatic sensors based on a dimension of the shot region.

45. The system according to claim 43, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section from each of the plurality of electrostatic sensors based on a position, of the shot region, in the wafer.

46. The system according to claim 43, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section from each of the plurality of electrostatic sensors based on an arrangement of chip regions in the shot region.

47. A device manufacturing method comprising the steps of:  
exposing the substrate using the lithography system of claim 43; and  
developing the exposed substrate.

48. A scanning exposure apparatus for exposing a substrate with a pattern of a mask by scanning the mask and the substrate relative to a slit-shaped exposure beam, the exposure apparatus comprising:

an electrostatic sensor having a plurality of detection sections arranged in a direction perpendicular to a scanning direction of the mask and substrate; and

a controller that selects at least one detection section from the plurality of detection sections and detects a height of a substrate surface based upon an output of the selected detection section.

49. The apparatus according to claim 48, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is further arranged to select at least one detection section based on a dimension of the shot region.

50. The apparatus according to claim 48, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section based on a position, of the shot region, in the wafer.

51. The apparatus according to claim 48, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section based on an arrangement of chip regions in the shot region.

52. A device manufacturing method comprising the steps of:  
exposing the substrate using the scanning exposure apparatus of claim 48; and  
developing the exposed substrate.

53. A scanning exposure apparatus for exposing a substrate with a pattern of a mask by scanning the mask and the substrate relative to a slit-shaped exposure beam, the exposure apparatus comprising:  
a plurality of electrostatic sensors arranged in a scanning direction of the mask and the substrate, wherein each of the plurality of electrostatic sensors has a plurality of detection sections arranged in a direction perpendicular to the scanning direction; and  
a controller that selects at least one detection section from each of the plurality of electrostatic sensors and detects a height of a substrate surface based upon outputs of the selected detection sections of the plurality of electrostatic sensors.

54. The apparatus according to claim 53, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section from each of the plurality of electrostatic sensors based on a dimension of the shot region.

55. The apparatus according to claim 53, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section from each of the plurality of electrostatic sensors based on a position, of the shot region, in the wafer.

56. The apparatus according to claim 53, wherein the substrate is a wafer in which a plurality of shot regions to be exposed are arranged, and the controller is arranged to select at least one detection section from each of the plurality of electrostatic sensors based on an arrangement of chip regions in the shot region.

57. A device manufacturing method comprising the steps of:  
exposing the substrate using the scanning exposure apparatus of claim 53; and  
developing the exposed substrate. --